IN THE CLAIMS

Please amend the claims as follows:

1-21. (Cancelled)

22. (Currently Amended) A method of manufacturing a load sensor, comprising:

forming a glass layer on a substrate made of metal;

providing glass paste;

forming an adjusting layer by applying the glass paste onto the glass layer and firing the applied glass paste;

forming a plurality of wirings on the adjusting layer; and

forming a strain-sensitive resistor element connected among the plurality of wirings by applying resistor element paste onto the adjusting layer and firing the resistor element paste, wherein a thermal expansion coefficient of the adjusting layer is closer to a thermal expansion coefficient of the strain-sensitive resistor element than to a thermal expansion coefficient of the glass layer,

wherein said providing the glass paste comprises:

dispersing ceramic powder in solvent and binder as to have a viscosity which is not smaller than 0.01 poises and is smaller than 100 poises, and

dispersing glass powder in the solvent and the binder including the ceramic powder dispersed therein to have a viscosity which is not smaller than 100 poises and is smaller than 10,000 poises.

23. (Original) The method as defined in claim 22, further comprising

forming a protective layer covering the strain-sensitive resistor element and respective portions of the plurality of wirings.

24. (Original) The method as defined in claim 22, wherein the substrate has a thickness not smaller than 1mm.

25. (Original) The method as defined in claim 22, wherein said forming the strain-sensitive resistor element comprises firing the applied resistor element paste at a temperature which is not lower than 400°C and is lower than 1,000°C.

26. (Original) The method as defined in claim 22, wherein said forming an adjusting layer comprises firing the applied glass paste at a temperature ranging from 400°C to 900°C.

27. (Original) The method as defined in claim 22, wherein the glass paste includes 5wt% to 40wt% of ceramic powder dispersed therein.

28. (Cancelled)

29. (Cancelled)

30. (Original) The method as defined in claim 22, wherein said forming the glass layer comprises

forming a glass layer including an electrode therein.

31. (New) A method of manufacturing a load sensor, comprising:

forming a glass layer on a substrate made of metal;

providing glass paste;

forming an adjusting layer by applying the glass paste onto the glass layer and firing the applied glass paste;

forming a plurality of wirings on the adjusting layer; and

forming a strain-sensitive resistor element connected among the plurality of wirings by applying resistor element paste onto the adjusting layer and firing the resistor element paste, wherein a thermal expansion coefficient of the adjusting layer is closer to a thermal expansion coefficient of the strain-sensitive resistor element than to a thermal expansion coefficient of the glass layer,

wherein said providing the glass paste comprises:

dispersing ceramic powder in solvent and dispersant as to have a viscosity which is not smaller than 0.01 poises and is smaller than 100 poises; and

dispersing glass powder in the solvent and the dispersant including the ceramic powder dispersed therein as to have a viscosity which is not smaller than 100 poises and is smaller than 10,000 poises.

32. (New) The method as defined in claim 31, further comprising:

forming a protective layer covering the strain-sensitive resistor element and respective portions of the plurality of wirings.

33. (New) The method as defined in claim 31, wherein the substrate has a thickness not smaller than 1mm.

34. (New) The method as defined in claim 31, wherein said forming the strain-sensitive resistor element comprises firing the applied resistor element paste at a temperature which is not lower than 400°C and is lower than 1,000°C.

35. (New) The method as defined in claim 31, wherein said forming an adjusting layer comprises firing the applied glass paste at a temperature ranging from 400°C to 900°C.

36. (New) The method as defined in claim 31, wherein the glass paste includes 5wt% to 40wt% of ceramic powder dispersed therein.

37. (New) The method as defined in claim 31, wherein said forming the glass layer comprises

forming a glass layer including an electrode therein.